



Click [here](#) for the 3D model.

| Dimensions | |
|------------|-----------------|
| Chip Size | 1206 |
| L | 3.3mm +/-0.4mm |
| W | 1.6mm +/-0.35mm |
| T | 1.6mm +/-0.20mm |
| B | 0.6mm +/-0.25mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 330mm, Plastic Tape |
| Packaging Quantity | 8000 |

| General Information | |
|---------------------|--|
| Series | ESD SMD Comm COG |
| Style | SMD Chip |
| Description | SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I |
| Features | Temperature Stable, Low ESR, Class I |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 36 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|------------------------|
| Capacitance | 0.047 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 1% |
| Voltage DC | 100 VDC |
| ESD Level per AEC-Q200 | 25,000 V ESD Level |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 21.2766 GOhms |

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